

Attorney Docket No. 2269-5709US (02-1462.00/US)

DECLARATION FOR PATENT APPLICATION (WITH POWER OF ATTORNEY)

As an inventor named below or on any attached continuation page, I hereby declare that:
My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled SEMICONDUCTOR SUBSTRATES INCLUDING I/O REDISTRIBUTION USING WIRE BONDS AND ANISOTROPICALLY CONDUCTIVE FILM, METHODS OF FABRICATION AND ASSEMBLIES INCLUDING SAME, the specification of which (check one):

- ☐ is attached hereto.
☒ was filed on August 4, 2003 as United States application serial no. 10/634,123 and was amended on _____.
☐ was filed on _____ as PCT international application no. _____ and was amended under PCT Article 19 on _____.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to the patentability of the subject matter claimed in this application, as "materiality" is defined in Title 37, Code of Federal Regulations § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate or § 365(a) of any PCT international application(s) designating at least one country other than the United States of America listed below and on any attached continuation page and have also identified below and on any attached continuation page any foreign application for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America having a filing date before that of the application(s) on which priority is claimed.

Prior foreign/PCT application(s):

			Priority	Claimed
<u>200303830-4</u>	<u>SG</u>	<u>22 July 2003</u>	<u>X</u>	
(number)	(country)	(day/month/year filed)	Yes	No
<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>
(number)	(country)	(day/month/year filed)	Yes	No

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) or § 365(c) of PCT international application(s) designating the United States of America listed below and on any attached continuation page and, insofar as the subject matter of each of the claims of this application is not disclosed in any such prior application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to

DECLARATION FOR PATENT APPLICATION
(continuation page)

Invention Title: SEMICONDUCTOR SUBSTRATES INCLUDING I/O REDISTRIBUTION USING WIRE BONDS AND ANISOTROPICALLY CONDUCTIVE FILM, METHODS OF FABRICATION AND ASSEMBLIES INCLUDING SAME

patentability as defined in Title 37, Code of Federal Regulations § 1.56 which became available between the filing date of such prior application and the national or PCT international filing date of this application:

_____	_____	_____
(application serial no.)	(filing date)	(status—pending, patented or abandoned)
_____	_____	_____
(application serial no.)	(filing date)	(status—pending, patented or abandoned)

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below:

_____	_____
(provisional application no.)	(filing date)

I hereby appoint the following Registered Practitioners to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

David V. Trask, Reg. No. 22,012	William S. Britt, Reg. No. 20,969
Laurence B. Bond, Reg. No. 30,549	Joseph A. Walkowski, Reg. No. 28,765
James R. Duzan, Reg. No. 28,393	H. Dickson Burton, Reg. No. 48,396
Allen C. Turner, Reg. No. 33,041	Edgar R. Cataxinos, Reg. No. 39,931
Kent S. Burningham, Reg. No. 30,453	Brick G. Power, Reg. No. 38,581
Kevin K. Johanson, Reg. No. 38,506	Krista Weber Powell, Reg. No. 47,867
Shawn G. Hansen, Reg. No. 42,627	Bretton L. Crockett, Reg. No. 44,632
Tawni L. Wilhelm, Reg. No. 47,456	Bradley B. Jensen, Reg. No. 46,801
Andrew F. Nilles, Reg. No. 47,825	Greg T. Warder, Reg. No. 50,208
Katherine A. Hamer, Reg. No. 47,628	Marcus S. Simon, Reg. No. 50,258
Trent N. Butcher, Reg. No. 51,518	G. Scott Dorland, Ph.D., Reg. No. 51,622
Michael L. Lynch, Reg. No. 30,871	Charles B. Brantley II, Reg. No. 38,086

Address all correspondence to: Joseph A. Walkowski, telephone no. (801) 532-1922.


TRASKBRITT, PC
P.O. Box 2550
Salt Lake City, Utah 84110

DECLARATION FOR PATENT APPLICATION
(continuation page)

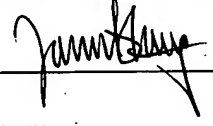
Invention Title: SEMICONDUCTOR SUBSTRATES INCLUDING I/O REDISTRIBUTION USING WIRE BONDS AND ANISOTROPICALLY CONDUCTIVE FILM, METHODS OF FABRICATION AND ASSEMBLIES INCLUDING SAME

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

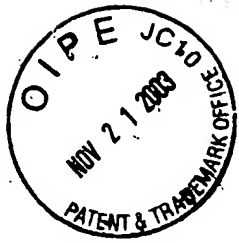
Full name of first joint inventor: Edmund Koon Tian Lua

Inventor's signature  Date 09/26/03
Residence: Singapore
Citizenship: Republic of Singapore
Post Office Address: Block 107C Edgefield Plains, Apt #13-126, Singapore 823107

Full name of second joint inventor: Nam Yin Leng

Inventor's signature  Date 09/26/2003
Residence: Singapore
Citizenship: Republic of Singapore
Post Office Address: Block 637 Veerasamy Road, Apt. #03-125, Singapore 200637

Document in ProLaw



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Lua et al.
Serial No.: 10/634,123
Filed: August 4, 2003
Title: SEMICONDUCTOR SUBSTRATES INCLUDING I/O REDISTRIBUTION USING WIRE BONDS AND ANISOTROPICALLY CONDUCTIVE FILM, METHODS OF FABRICATION AND ASSEMBLIES INCLUDING SAME

Examiner: Unknown
Group Art Unit: Unknown
Attorney Docket No.: 2269-5709US (02-1462.00/US)

POWER OF ATTORNEY BY ASSIGNEE
AND CERTIFICATE UNDER 37 CFR § 3.73(b)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

MICRON TECHNOLOGY, INC., assignee of the entire right, title and interest by assignment from the inventor(s) in the above-identified application, hereby appoints the following attorneys and agents:

David V. Trask, Reg. No. 22,012	William S. Britt, Reg. No. 20,969	Laurence B. Bond, Reg. No. 30,549
Joseph A. Walkowski, Reg. No. 28,765	James R. Duzan, Reg. No. 28,393	H. Dickson Burton, Reg. No. 48,396
Allen C. Turner, Reg. No. 33,041	Edgar R. Cataxinos, Reg. No. 39,931	Kent S. Burningham, Reg. No. 30,453
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Shawn G. Hansen, Reg. No. 42,627	Bretton L. Crockett, Reg. No. 44,632	Tawni L. Wilhelm, Reg. No. 47,456
Bradley B. Jensen, Reg. No. 46,801	Andrew F. Nilles, Reg. No. 47,825	Greg T. Warder, Reg. No. 50,208
Katherine A. Hamer, Reg. No. 47,628	Marcus S. Simon, Reg. No. 50,258	Trent N. Butcher, Reg. No. 51,518
G. Scott Dorland, Ph.D., Reg. No. 51,622	Jeffery M. Michelsen, Reg. No. 50,978	Michael L. Lynch, Reg. No. 30,871
Charles B. Brantley II, Reg. No. 38,086		

as its attorneys with full power of substitution to prosecute this application and all applications claiming filing date priority therefrom and to transact all business in the U.S. Patent and Trademark Office in connection therewith.

The above-identified assignee hereby elects, pursuant to 37 C.F.R. § 3.71, to conduct the prosecution of the above-identified patent application to the exclusion of the inventor(s).

A chain of title from the inventor(s) of the above-identified patent application to the above-identified assignee is shown:

- ☐ In an assignment recorded in the U.S. Patent and Trademark Office at Reel _____, Frame _____.
- ☒ In an assignment filed herewith for recordation, a true copy of which is attached hereto.

The undersigned has reviewed the above-identified assignment and, to the best of his knowledge and belief, title is in the above-identified assignee.

The undersigned further avers that he is empowered to make and sign the foregoing certification on behalf of the above-identified assignee, and to take the action set forth herein on its behalf.

Please direct all communications regarding the above-identified application to:

Joseph A. Walkowski,
TRASKBRITT
P.O. Box 2550
Salt Lake City, UT 84110
Telephone: (801) 532-1922
Fax: (801) 531-9168

Respectfully submitted,

MICRON TECHNOLOGY, INC.

Date: 11-12-2007

By: [Signature]
Michael L. Lynch, Esq.
Reg. No. 30,871
Chief Patent Counsel,
MICRON TECHNOLOGY, INC.

ASSIGNMENT

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, each undersigned ASSIGNOR does hereby:

SELL, ASSIGN AND TRANSFER to Micron Technology, Inc. ("ASSIGNEE"), a corporation of the state of Delaware having a place of business at Mailstop 525, 8000 South Federal Way, Boise, ID 83706, the entire right, title and interest for the United States and all foreign countries in and to any and all improvements which are disclosed in the Application for United States Letters Patent Serial No. 10/634,123 filed on August 04, 2003, and entitled **SEMICONDUCTOR SUBSTRATES INCLUDING I/O REDISTRIBUTION USING WIRE BONDS AND ANISOTROPICALLY CONDUCTIVE FILM, METHODS OF FABRICATION AND ASSEMBLIES INCLUDING SAME**, such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent or the legal equivalent thereof which have been or may be filed in the United States and all foreign countries relating to any of such improvements; all original, reexamined and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application made in the United States;

AUTHORIZE the ASSIGNEE to apply for and receive any and all United States and foreign patents relating to such improvements in its own name;


AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to and in the name of the ASSIGNEE;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement or encumbrance affecting the rights and property herein conveyed has been or will be made or entered into by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

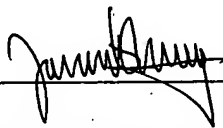
COVENANT, when requested and at the expense of the ASSIGNEE, to carry out in good faith the intent and purpose of this assignment, to execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications relating to any and all such improvements; to execute all rightful oaths, declarations, assignments, powers of attorney and other papers; to communicate to the ASSIGNEE all facts and provide to the ASSIGNEE all documents and things known and accessible to the undersigned relating to such improvements and the history thereof, and testify as to the same in any interference, litigation or other proceeding relating thereto; and generally to do everything possible which the ASSIGNEE shall consider desirable for vesting title to such improvements in the ASSIGNEE, and to secure, maintain, defend and enforce valid and enforceable patent protection for such improvements;

AGREE and **ACKNOWLEDGE** that the **SALE, ASSIGNMENT AND TRANSFER** of rights and property set forth herein is and shall be **IRREVOCABLE** and **BINDING** upon the heirs, assigns, representatives and successors of each undersigned **ASSIGNOR** and **EXTEND** to the successors, assigns and nominees of the **ASSIGNEE**.

ASSIGNORS:



Date 09/26/03
Edmund Koon Tian Lua
Residing at: Block 107C Edgefield Plains, Apt # 13-126, Singapore



Date 09/26/03
Nam Yin Leng
Residing at: Block 637 Veerasamy Road, Apt. #03-125, Singapore

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